

S P E C I F I C A T I O N

BE IT KNOWN THAT I, TAKEHIRO FUJII, residing at c/o
ROHM CO., LTD., 21, Saiin Mizosaki-cho, Ukyo-ku, Kyoto-shi,
Japan, subjects of Japan, have invented certain new and
useful improvements in

CHIP TYPE LIGHT EMITTING DEVICE

of which the following is a specification:-

SPECIFICATION

CHIP TYPE LIGHT EMITTING DEVICE

TECHNICAL FIELD

5 The present invention relates to the ultra small-sized chip type light emitting device using a light emitting diode (LED) chip which can obtain the symmetric luminous intensity distribution in a longitudinal direction on a board and can enhance wire bonding reliability.

10

BACKGROUND

 A small-sized chip type light emitting device with a light emitting diode (LED) chip is known as a conventional light emitting source. Figure 2 is a perspective view showing an example of such chip type light emitting device. Figure 2 illustrates that a pair of electrode patterns 3 and 4 comprised of conductive layer such as copper (Cu) plate layer is formed at the both ends of the board 2. One electrode pattern 3 consists of the surface electrode 3a, side face electrode 3b and back electrode 3c.

20

 The other electrode pattern 4 also consists of the surface electrode 4a, side face electrode 4b and back electrode 4c. The side face electrode 3b and side face electrode 4b of a pair of electrode patterns 3 and 4 form several elliptical through holes in parallel on an original large-sized board on which the board 2 can be obtained by dividing, the internal surface of the elliptical though holes is plated with Cu, etc.,

25

and the surface electrodes 3a/4a and back electrodes 3c/4c of a pair of electrode patterns 3 and 4 are connected to each other.

The pad 3p is formed on the surface electrode 3a of one electrode pattern 3 and the LED chip 1 is mounted there by die-bonding. One end 5a of the metal wire 5 is connected electrically to the electrode 1a of the LED chip 1 by wire bonding. The other end 5b of the metal wire 5 is connected electrically to the surface electrode 4a of the other electrode pattern 4 by wire bonding. The ultrasonic wave is used in this wire bonding.

The LED chip 1 mounted on the board 2, in which the lower electrode is connected to the surface electrode 3a of one electrode pattern 3 by the wiring bonding, and the metal wire 5 connected electrically to the upper electrode 1a of the LED chip 1 and to the surface electrode 4a of the other electrode pattern 4 by wire bonding are sealed with the translucent resin mold 6. The positions of both ends of this translucent resin mold 6 are located separately from each other at the inside of both ends of the board 2. The chip type light emitting device 20 is formed as mentioned above.

At the handling such as transportation, etc. for automatic mounting to a printed board, etc., the translucent resin mold 6 is picked up by a chuck and the chip type light emitting device 20 is transferred. In the configuration shown in Figure 2, both ends of the translucent resin mold 6 are located at the inside of the surface electrodes 3a and 4a of

a pair of electrode patterns 3 and 4. Therefore, the length of the translucent resin mold 6 is shorter than that of the board 2 of the chip type light emitting device 20, and the contact area for picking up becomes smaller, so if the size of the board 2 becomes 1.6 mm (length) x 0.8 mm (width) or less, the handling cannot be performed smoothly.

Figure 3 and Figure 4 are perspective views showing an example of conventional another chip type light emitting device and the example illustrates that the semi-circular notches 7 and 8 have been formed at both ends of the board 2. Figure 5 is a characteristics diagram showing the distribution of luminous intensity I of the chip type light emitting device of Figure 3. In Figure 3 and Figure 4, the same places as Figure 2 or the points corresponding to Figure 2 are marked with the same symbols. In the example of Figure 3, the side face electrodes 3b and 4b of a pair of electrode patterns 3 and 4 are formed at the internal face of the semi-circular notches 7 and 8 which are formed at both ends of the board 2.

The surface electrodes 3a and 4a of a pair of electrode patterns 3 and 4 extend to a place where those electrodes cover the upper faces of the notches 7 and 8 and both ends of the translucent resin mold 6 and both longitudinal ends of the board 2 are aligned. In the example of Figure 3, the surfaces of the notches 7 and 8 are covered with the surface electrodes 3a and 4a of a pair of electrode patterns 3 and 4. Therefore, the resin does not flow into the notches 7 and 8 when the

translucent resin mold 6 is processed.

In the example of Figure 3, both ends of the translucent resin mold 6 are located at both longitudinal ends of the board 2. Therefore, this example has the advantage of securing the surface area of the translucent resin mold 6 to the extent that the said handling can be performed smoothly even if the chip type light emitting device 30 is downsized.

However, assuming that both ends of the translucent resin mold 6 are located at both longitudinal ends of the board 2 as shown in Figure 3, if the board size becomes small, e.g., 1.6 mm x 0.8 mm, the LED chip cannot be centered on the board 2 as shown in Figure 4.

In the example of chip type light emitting device 40 of Figure 4, the LED chip 1 is mounted at a position shifted to a longitudinal center of the board 2 and the other end 5b of the metal wire 5 is bonded at a position close to the end of the board 2. That is, the other end 5b of the metal wire 5 is bonded at a position where the surface electrode 4b of the electrode pattern 4 covers the notch 8.

As described above, a position to bond the other end 5b of the metal wire is located on the surface electrode 4b which covers the upper face of the notch 8. Therefore, the notch 8 is located under a place where wire bonding is performed and the mechanical strength of horn support deteriorates at wire bonding with the ultrasonic wave.

Therefore, enough pressure cannot be applied to the horn which propagates the ultrasonic wave at the ultrasonic wave

processing and the surface electrodes 4b of the electrode pattern 5 and the other end 5b of the metal wire cannot be bonded completely to each other by the ultrasonic wave. To enhance the reliability of bonding with the ultrasonic wave, the configuration illustrated in Figure 3 is adopted. However, in Figure 3, the LED chip 1 is mounted at the off-centered position on the board 2.

In the example of Figure 3, the LED chip 1 cannot be centered on the board 2. As a result, the LED chip 1 is located at the decentered position on the translucent resin mold 6 also. So, as shown in the luminous intensity characteristics diagram of Figure 5, there was a problem that the symmetric luminous intensity distribution cannot be obtained in a longitudinal direction of the board.

DISCLOSURE OF INVENTION

The present invention was made taking such problem into consideration and the purpose of the present invention is to offer the ultra small-sized chip type light emitting device which can obtain the symmetric luminous intensity distribution in a longitudinal direction of the board even if the board is downsized and which can enhance wire bonding reliability.

The chip type light emitting device offered by the present invention comprising: a board of nearly rectangular shape in a plane view; first and second electrode patterns formed at both ends of a surface of the board; a light emitting diode (LED) chip mounted on the first electrode pattern; a

metal wire connected to the LED chip and the second electrode pattern by wire bonding; and a translucent resin mold which seals the LED chip and the metal wire;

wherein one notch is formed at one end of the board at the first electrode pattern side and two notches are formed at both sides of the other end of the board at the second electrode pattern side, and the positions at both ends of the translucent resin mold are arranged to the positions at both ends in a longitudinal direction of the board.

The preferred embodiment of the present invention features that the LED is almost centered on the board.

The preferred embodiment of the present invention features that the board size is 1.6 mm x 0.8 mm or less.

The preferred embodiment of the present invention features that the metal wire is connected to the LED chip and the surface electrode of the second electrode pattern, which is located between the two notches formed at both sides of the other end of the board at the second electrode pattern side, by wire bonding.

The preferred embodiment of the present invention features that one notch formed at the one end of the board at the first electrode pattern side is semi-cylindrical and the two notches formed at both sides of the other end of the board at the second electrode pattern side are quarter-cylindrical.

According to the present invention, two notches are formed at both side of one end of the board. Therefore, even

if a wire bonding position is close to the end of the board,
wire bonding of the second electrode pattern and metal wire
is made stably on the board between such two notches and the
LED chip can be centered on the board. Therefore, the ideal
5 symmetric luminous intensity characteristics can be obtained
in a longitudinal direction of the board.

One notch is formed at one end of the board and two notches
are formed at the other end. So, the polarity of the LED chip
can be checked easily. If the translucent resin mold is milk
10 white, the LED chip embedded in the translucent resin mold
is illegible. However, one notch is formed at one end of the
board and two notches are formed at the other end. Therefore,
it is obvious that the electrode structure is asymmetric and
the polarity can be checked easily because of the appearance
15 of chip type light emitting device.

Moreover, the positions of both ends of translucent
resin mold are arranged to the positions of both ends in a
longitudinal direction of the board. Therefore, the contact
area for picking up can be increased and handling process can
20 be performed smoothly to ultra small-sized chip type light
emitting device.

BRIEF DESCRIPTION OF THE DRAWINGS

Figure 1 is a perspective view which illustrates the chip
25 type light emitting device with the embodiment of the present
invention;

Figure 2 is a perspective view which summarizes a

conventional chip type light emitting device;

Figure 3 is a perspective view which summarizes a conventional chip type light emitting device;

Figure 4 is a perspective view which summarizes a
5 conventional chip type light emitting device;

Figure 5 is a characteristics diagram which shows the luminous intensity in a longitudinal direction of a conventional chip type light emitting device; and

Figure 6 is a characteristics diagram which shows the
10 luminous intensity in a longitudinal direction of the chip type light emitting device with the embodiment of the present invention.

DESCRIPTION OF THE PREFERRED EMBODIMENTS

15 Now, a description will be given in more detail of preferred embodiments of the present invention with reference to the accompanying drawings. Figure 1 is a perspective view which illustrates the chip type light emitting device 10 with the embodiment of the present invention.

20 A pair of electrode patterns 13 and 14 comprised of conductive layer such as copper (Cu) plate layer is formed at the both ends of the board 12. One electrode pattern 13 consists of the surface electrode 13a, side face electrode 13b and back electrode 13c.

25 The other electrode pattern 14 also consists of the surface electrode 14a, side face electrode 14b and back electrode 14c. The side face electrode 13b and side face

electrode 14b of a pair of electrode patterns 13 and 14 form several elliptical through holes in parallel on an original large-sized board on which the board 2 can be obtained by dividing, the internal surface of the elliptical though holes is plated with Cu, etc., and the surface electrodes 13a/14a and back electrodes 13c/14c of a pair of electrode patterns 13 and 14 are connected to each other.

The pad 13p is formed on the surface of the board 12 to be electrically connected with the surface electrode 13a of one electrode pattern 13 and the LED chip 11 is mounted there by die-bonding. One end 15a of the metal wire 15 is connected electrically with the electrode 11a of the LED chip 11 by wire bonding. The other end 15b of the metal wire 15 is connected electrically with the surface electrode 14a of the other electrode pattern 14 by wire bonding. The ultrasonic wave is used in this wire bonding.

The LED chip 11 mounted on the board 12, in which the lower electrode is connected to the surface electrode 13a of one electrode pattern 13 by the die-bonding, and the metal wire 15 connected electrically with the upper electrode 11a of the LED chip 11 and with the surface electrode 14a of the other electrode pattern 14 by wire bonding are sealed with the translucent resin mold 16.

In Figure 1, the shape of the board 12 is nearly rectangular shape in a plan view (e.g., 10 mm in length x 0.5 mm in width) and the first electrode pattern 13 and the second electrode pattern 14 are formed at both ends in a longitudinal

direction of the surface of the board 12. The semi-cylindrical notch 17, which penetrates perpendicularly, is formed at the center of one end of the board 2. Moreover, the notches 18a and 18b, which penetrate perpendicularly, at both sides in a crosswise direction (width direction), are formed at the other end of the board 12.

The surface electrodes 13a and 14a of the first and second electrodes 13 and 14 project like eaves on the notch 17 at one side and on the two notches 18a and 18b at the other side. The side electrodes 13b and 14b, which are connected to the surface electrodes 13a and 14a, are formed and exposed on the internal side walls of such notch 17 and such notches 18a and 18b. Moreover, the back electrodes 13c and 14c are formed at both ends of the back of the board 12.

The two notches 18a and 18b can be formed at both side at one end of the board 12 by selecting the position to form the notches when several chip type light emitting devices are manufactured from one large-sized board equipped with several LED chips and by setting the positions to cut the large-sized board longitudinally and transversely to form individual chip type light emitting devices to the positions of the notches 18a and 18b shown in Figure 1.

The LED chip 11, of which lower face electrode is connected to the surface electrode 13a, is centered on the surface of the board 2 and the upper face electrode 11a of the LED chip 1 is connected to the surface electrode 14a at one end 15a of the metal wire 15 such as gold (Au) by wire

bonding. The metal wire 15 is arranged from the center of the board 12 to the other end of the board 2, which is the center at the width direction, that is, toward the position of the surface electrode 14a between the notches 18a and 18b. The
5 other end 15b of the metal wire is connected to the surface electrode 14a at the end of the board 12.

The surface electrodes 13a and 14a of the first electrode pattern 13 and the second electrode pattern 14 cover the notch 17 and the notches 18a and 18b, and the ends of the first and
10 second electrode patterns 13 and 14 are arranged at both ends of the board 12. Moreover, the positions of both ends of translucent resin mold 16 are arranged to the positions of both ends of the board 12.

In the configuration of Figure 1, a part of the board
15 12 is located between the two notches 18a and 18b. Therefore, a connecting position of the other end 15b of the metal wire 5 and the surface electrode 14b of the electrode pattern 4 is formed on the board 2. A lower part of horn of ultrasonic wave device is supported by this board. So, enough pressure
20 can be applied, and the other end 15b of the metal wire 15 and the surface electrode 14b of the electrode pattern 14 can be bonded completely by the ultrasonic wave. Therefore, the wire bonding reliability can be enhanced.

Figure 6 is a characteristics diagram which shows the
25 distribution of luminous intensity I of the chip type light emitting device of Figure 1. For the chip type light emitting device of Figure 1, as shown in Figure 6, the ideal symmetric

luminous intensity characteristics can be obtained in a longitudinal direction of the board 12 by centering the LED chip 1 on the board 12. Also, wire bonding can be made stably by extending the other end 15b of the metal wire 15 to a position close to the end of the board 2.

Furthermore the one notch 17 is formed at one end of the board 12 and the two notches 18a and 18b are formed at the other end. So, the polarity of the LED chip 11 can be checked easily according to the number of notches. If the translucent resin mold 16 is milk white, the LED chip 11 embedded in the translucent resin mold 16 is illegible. However, even in this case, the polarity can be checked easily based on the appearance of chip type light emitting device 10.

In ultra small-sized chip type light emitting device of which size is 10 mm in length x 0.5 mm in width, it is difficult to show the polarity in resist. It is very useful to check the polarity according to the number of formed notches as described above.

Moreover, the positions of both ends of the translucent resin mold 16 are arranged to the positions of longitudinal ends of the board 12

Moreover, the positions of both ends of translucent resin mold 16 are arranged to the positions of both ends in a longitudinal direction of the board 12. Therefore, the contact area for picking up can be increased and handling process can be performed smoothly to small-sized chip type light emitting device.